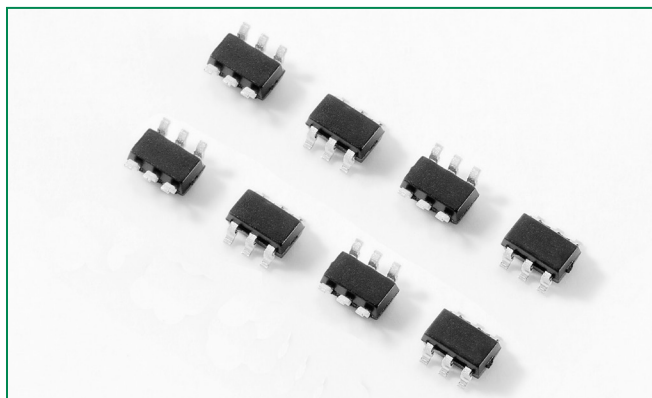


SP3019 0.3pF SOT23-6L 4 Channels Diode Array

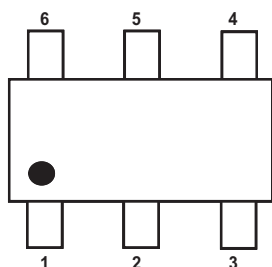


Description

The SP3019 integrates 4 channels of ultra low capacitance asymmetrical protection for electronic equipment that may experience destructive electrostatic discharges (ESD). These robust components can safely absorb repetitive ESD strikes above the maximum contact level specified in the IEC 61000-4-2 international standard ($\pm 8\text{kV}$ contact discharge) without performance degradation.

The extremely low off-state capacitance also makes it ideal for protecting high speed signal lines such as USB3.0, HDMI, USB2.0, and eSATA.

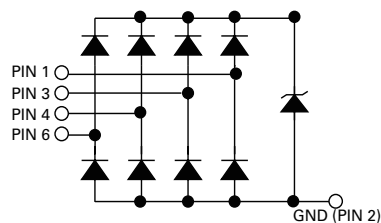
Pinout



Features

- ESD, IEC 61000-4-2, +22kV/-10kV contact, +22kV/-10kV air
- EFT, IEC 61000-4-4, 40A ($t_p=5/50\text{ns}$)
- Lightning, 2.5A (8/20 as defined in IEC 61000-4-5 2nd edition)
- Low capacitance of 0.3pF @0V, 3GHz (TYP) per I/O
- Low leakage current of 10nA (TYP) at 5V
- AEC-Q101 qualified
- Moisture Sensitivity Level (MSL-1)
- Halogen free, lead free and RoHS compliant

Functional Block Diagram



Applications

- LCD/PDP TVs
- External Storages
- DVD/Blu-ray Players
- Desktops
- MP3/PMP
- Set Top Boxes
- Smartphones
- Ultrabooks/Notebooks
- Digital Cameras

Life Support Note:

Not Intended for Use in Life Support or Life Saving Applications

The products shown herein are not designed for use in life sustaining or life saving applications unless otherwise expressly indicated.

Absolute Maximum Ratings

Symbol	Parameter	Value	Units
I_{PP}	Peak Current ($t_p=8/20\mu s$)	2.5	A
T_{OP}	Operating Temperature	-40 to 125	°C
T_{STOR}	Storage Temperature	-55 to 150	°C

CAUTION: Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the component. This is a stress only rating and operation of the component at these or any other conditions above those indicated in the operational sections of this specification is not implied.

Electrical Characteristics ($T_{OP}=25^\circ C$)

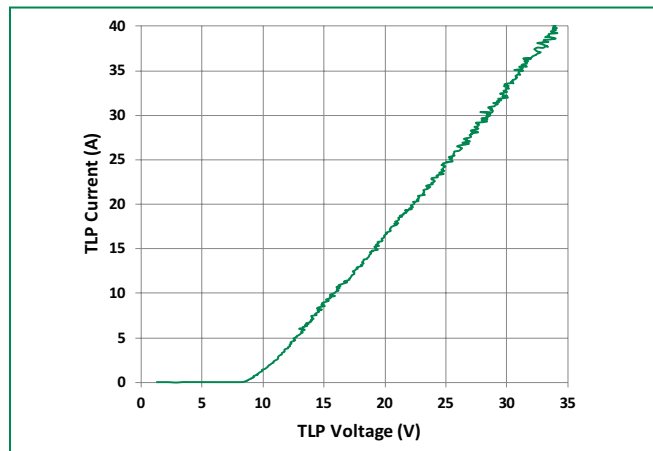
Parameter	Symbol	Test Conditions	Min	Typ	Max	Units
Reverse Standoff Voltage	V_{RWM}	$I_R \leq 1\mu A$			5.0	V
Breakdown Voltage	V_{BR}	$V_R=5V$, Any I/O to GND		0.01	0.50	μA
Reverse Voltage Drop	V_R	$I_R=1mA$		8.2		V
Clamp Voltage ¹	V_C	$I_{PP}=1A$, $t_p=8/20\mu s$, Fwd		10.5		V
		$I_{PP}=2A$, $t_p=8/20\mu s$, Fwd		11.5		V
Dynamic Resistance ²	R_{DYN}	TLP, $t_p=100ns$, I/O to GND		0.64		Ω
ESD Withstand Voltage ¹	V_{ESD}	IEC 61000-4-2 (Contact)	+22/-10			kV
		IEC 61000-4-2 (Air)	+22/-10			kV
Diode Capacitance	$C_{I/O-GND}$	Reverse Bias=0V, $f=3GHz$		0.3		pF
	$C_{I/O-I/O}$			0.18		

Note:

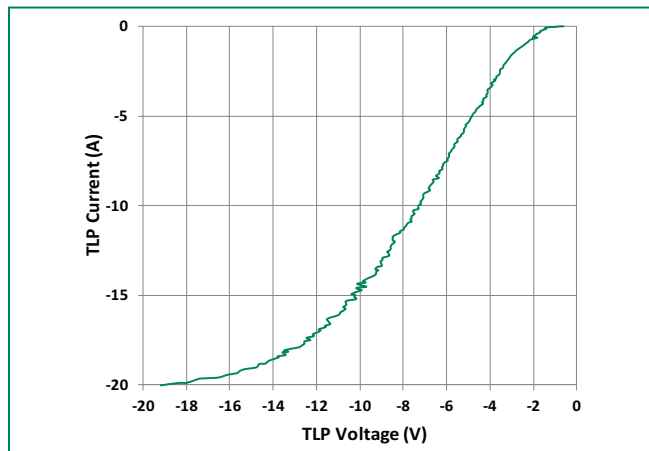
1. Parameter is guaranteed by design and/or component characterization.

2. Transmission Line Pulse (TLP) with 100ns width, 2ns rise time, and average window $t_1=70ns$ to $t_2=90ns$

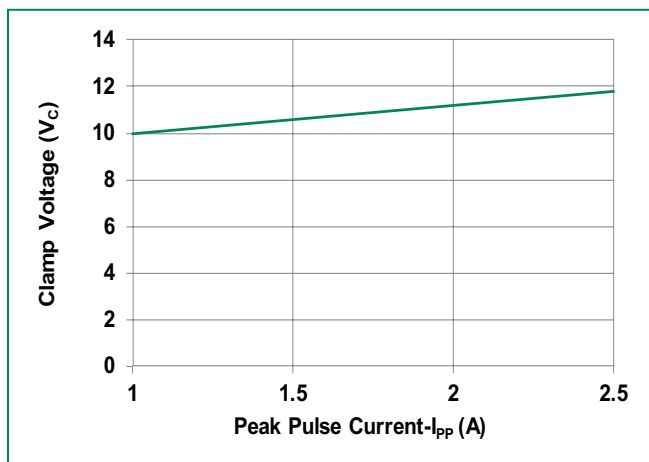
Positive Transmission Line Pulsing(TLP) Plot



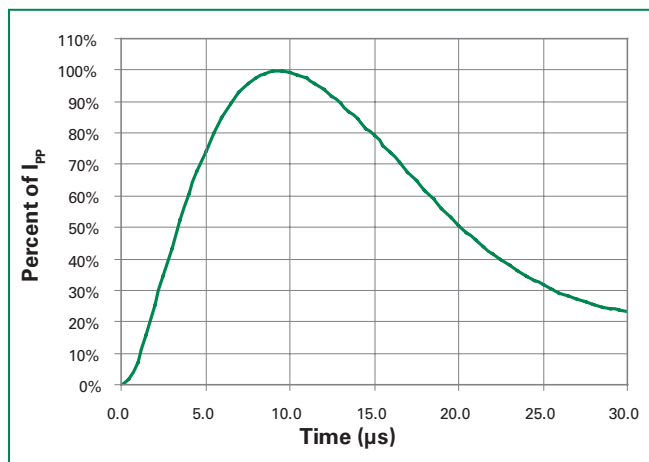
Positive Transmission Line Pulsing(TLP) Plot



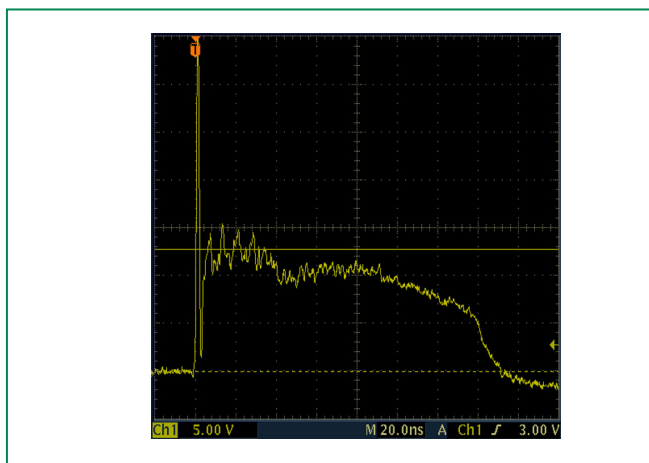
Clamping Voltage vs. I_{PP} for 8/20 μ S waveshape



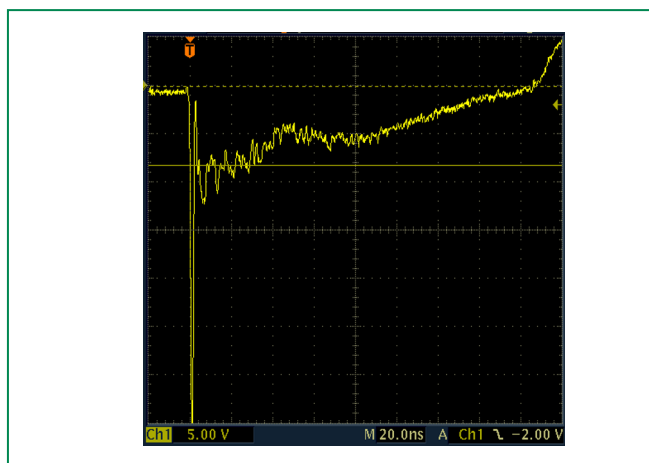
8/20 μ S Pulse Waveform



IEC 61000-4-2 +8 kV Contact ESD Clamping Voltage



IEC 61000-4-2 -8 kV Contact ESD Clamping Voltage

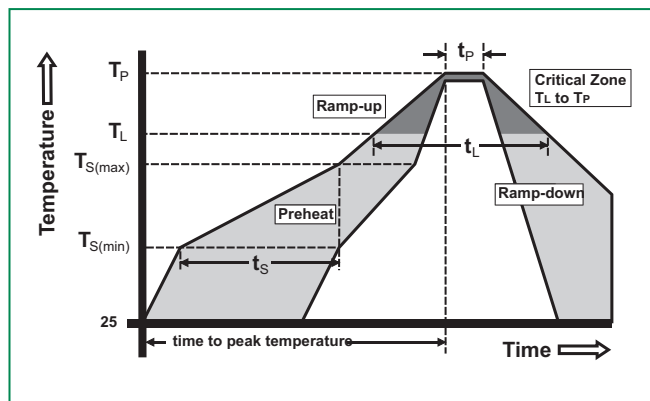


Soldering Parameters

Reflow Condition		Pb – Free assembly
Pre Heat	- Temperature Min ($T_{s(min)}$)	150°C
	- Temperature Max ($T_{s(max)}$)	200°C
	- Time (min to max) (t_s)	60 – 180 secs
Average ramp up rate (Liquidus) Temp (T_L) to peak		3°C/second max
$T_{s(max)}$ to T_L - Ramp-up Rate		3°C/second max
Reflow	- Temperature (T_L) (Liquidus)	217°C
	- Temperature (t_L)	60 – 150 seconds
Peak Temperature (T_P)		260 ^{+0/-5} °C
Time within 5°C of actual peak Temperature (t_p)		20 – 40 seconds
Ramp-down Rate		6°C/second max
Time 25°C to peak Temperature (T_P)		8 minutes Max.
Do not exceed		260°C

Ordering Information

Part Number	Package	Marking	Min. Order Qty.
SP3019-04HTG	SOT23-6	ACVD	3000



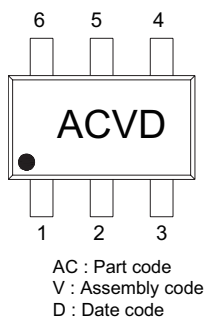
Product Characteristics

Lead Plating	Matte tin
Lead Material	Copper Alloy
Lead Coplanarity	0.0004 inches (0.102mm)
Substrate material	Silicon
Body Material	Molded Compound
Flammability	UL Recognized compound meeting flammability rating V-0.

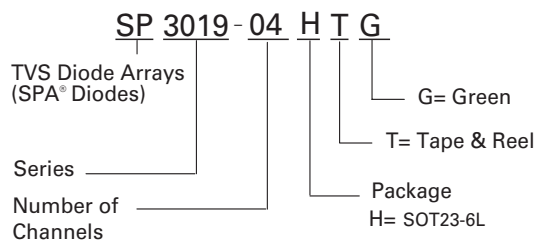
Notes :

1. All dimensions are in millimeters
2. Dimensions include solder plating.
3. Dimensions are exclusive of mold flash & metal burr.

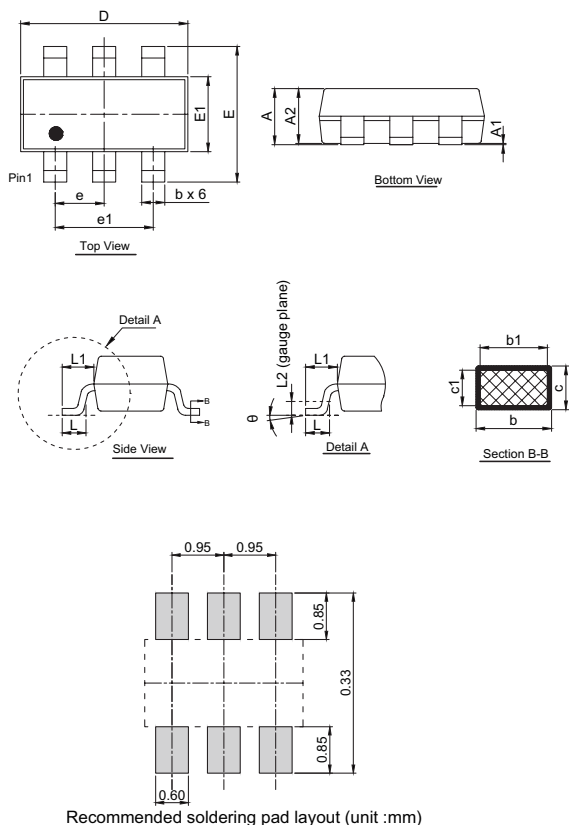
Part Marking System



Part Numbering System



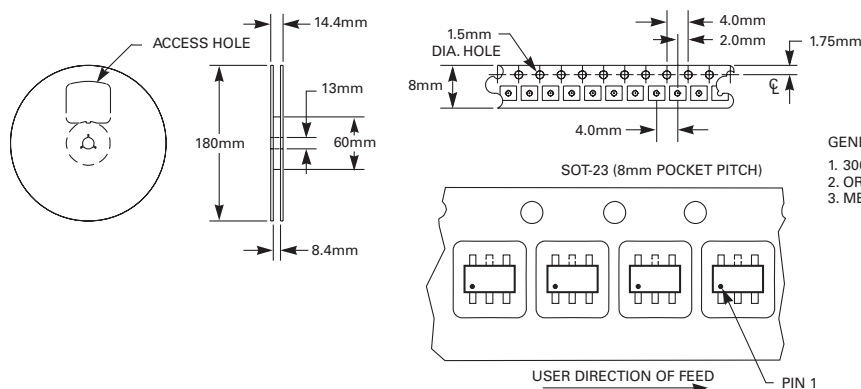
Package Dimensions — SOT23-6L



Symbol	Millimeters		
	Min	Nom	Max
A	-	-	1.45
A1	0.00	-	0.15
A2	0.90	1.15	1.30
b	0.30	-	0.50
b1	0.30	0.40	0.45
c	0.08	-	0.22
c1	0.08	0.13	0.20
D	2.75	2.90	3.05
E	2.60	2.80	3.00
E1	1.45	1.60	1.75
e	0.95 BSC		
e1	1.90 BSC		
L	0.30	0.50	0.60
L1	0.60 REF		
L2	0.25 BSC		
θ	0°	4°	8°

Embossed Carrier Tape & Reel Specification — SOT23-6L

8mm TAPE AND REEL



GENERAL INFORMATION
1. 3000 PIECES PER REEL.
2. ORDER IN MULTIPLES OF FULL REELS ONLY.
3. MEETS EIA-481 REVISION "A" SPECIFICATIONS.

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